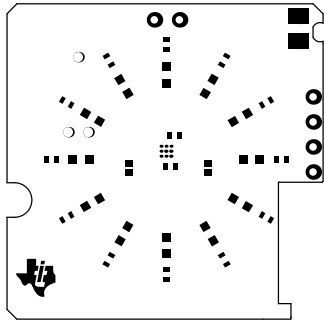
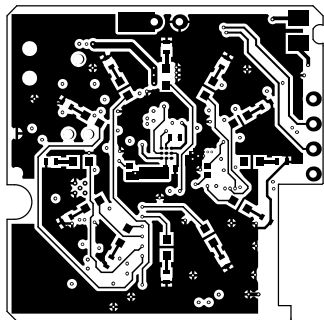


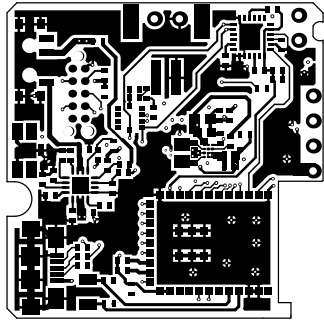
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP029	REV: A	SUN REV:
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 5/21/2014 18:51	TEXAS INSTRUMENTS	



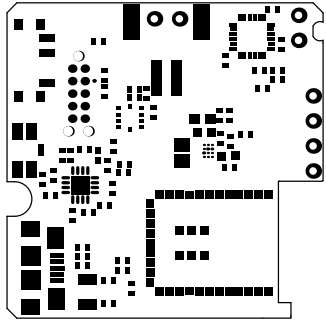
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP029	REV: A	SUN REV:
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 5/21/2014 18:51	TEXAS INSTRUMENTS	



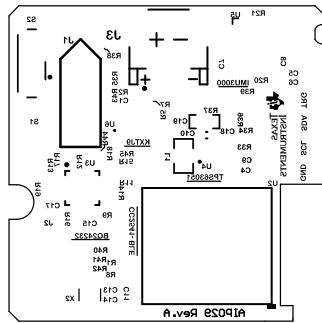
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP029	REV: A	SUN REV:
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 5/21/2014 18:51	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP029	REV: A	SUN REV:
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 5/21/2014 18:51	TEXAS INSTRUMENTS	

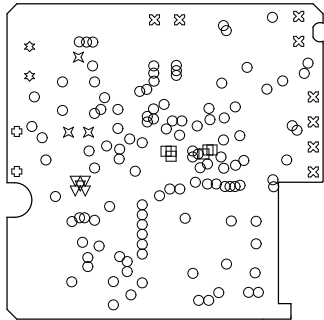


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP029	REV: A	SUN REV:
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 5/21/2014 18:51	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP029	REV: A	SUN REV:
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 5/21/2014 18:51	TEXAS INSTRUMENTS	

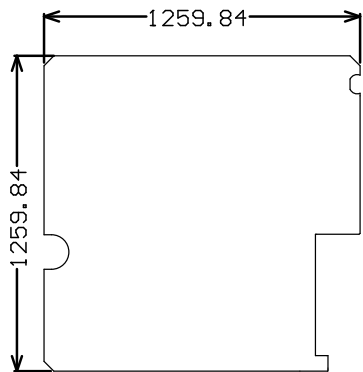
ALL VIAS TO BE FILLED AND PLATED SHUT.



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	6	6mil (0.152mm)	PTH	Round
▽	5	7.874mil (0.2mm)	PTH	Round
○	117	8mil (0.203mm)	PTH	Round
⊕	2	27.559mil (0.7mm)	PTH	Round
⊗	8	30mil (0.762mm)	PTH	Round
☆	2	35.433mil (0.9mm)	NPTH	Round
⊠	3	39.016mil (0.991mm)	NPTH	Round
143 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP029	REV: A	SUN REV:
LAYER NAME =			
PLOT NAME = Drill Drawing	GENERATED : 5/21/2014 18:51	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP029	REV: A	SUN REV:
LAYER NAME =			
PLOT NAME = Board Dimensions	GENERATED : 5/21/2014 18:51	TEXAS INSTRUMENTS	



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